

Heraeus



Heraeus Electronics Advanced Materials For Your Packaging Solutions

Invitation



If you want to stand out and stay ahead in the fast-changing semiconductor market, please be sure to visit Heraeus Electronics at the Semicon China.

Join us at **Booth Number 7601, Hall E7** to hear our experts' presentations. Get to speak with our product and technical experts and learn how our matched materials and other innovations can help you be competitive and succeed. Appreciation gift will also be given onsite.

Date: March 14-16, 2018 | Semicon China 2018
Venue: Shanghai New International Expo Center (SNIEC)

Program Schedule

Day 1 (March 14, Wednesday)

2:00 – 2:15 PM	New Sinter Paste for SiC devices Speaker: Mr. Clark Dai, Product Manager
2:30 – 2:45 PM	Presoldered DCB for Power Electronics Speaker: Mr. Tim Lu, Segment Manager
3:00 – 3:15 PM	Solder defects reduction in SiP Speaker: Dr. Zhang Rui Fen, Chief Chemist
3:30 – 3:50 PM	Bonding Wires for Power Electronics and Semiconductor applications Speaker: Mr. Song Jianbo, Bonding Wire Application Lab Supervisor

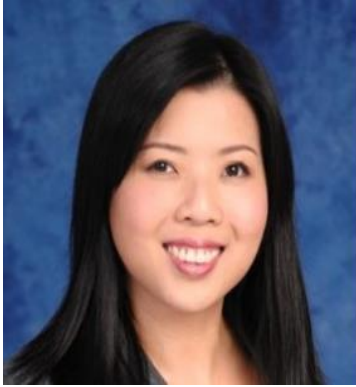
Day 2 (March 15, Thursday)

10:30 – 10:45 AM	Advanced Materials for SiP applications Speaker: Ms. Li-San Chan, Global Product Manager
11:00 – 11:15 AM	Solder defects reduction in SiP Speaker: Dr. Zhang Rui Fen, Chief Chemist
2:00 – 2:15 PM	New Sinter Paste for SiC devices Speaker: Mr. Clark Dai, Product Manager
2:30 – 2:45 PM	Presoldered DCB for Power Electronics Speaker: Mr. Tim Lu, Segment Manager
3:00 – 3:15 PM	Bonding Wires for Power Electronics and Semiconductor applications Speaker: Mr. Song Jianbo, Bonding Wire Application Lab Supervisor

Day 3 (March 16, Friday)

10:30 – 10:45 AM	New Sinter Paste for SiC devices Speaker: Mr. Clark Dai, Product Manager
11:00 – 11:15 AM	Presoldered DCB for Power Electronics Speaker: Mr. Tim Lu, Segment Manager
11:30 – 11:45 AM	Advanced Materials for SiP applications Speaker: Ms. Li-San Chan, Global Product Manager

Speakers



Ms. Li-San Chan is at her 21st year in the semiconductor, chip-making industry. Currently she is the Global Product Manager for Advanced Packaging solder materials at Heraeus Electronics. She embarked on the journey to seek solutions in Advanced Packaging at Applied Materials in 2014. Ms. Chan also began her career in 1997 at Applied Materials, held various positions in Process Engineering, Account Sales, and Regional Product Marketing. In 2007, she joined Advanced Micro-fabrication Equipment Inc (AMEC), based in Shanghai; where she successfully launched the company's first dry etch equipment into the market. Ms. Chan earned her Asia Pacific Executive MBA from National University of Singapore and has a Bachelor of Applied Science in Materials Engineering degree from Nanyang Technological University of Singapore.



Dr. Zhang, Ruifen is the Chief Chemist at Heraeus Electronics Advanced Packaging Innovation Department. Based in Singapore; she has more than 16 years of experience in solder paste development - including water soluble halogen free paste, fine pitch solder paste, and dipping & pin transfer paste for advanced packaging applications. She is also experienced in the development of high lead die attach paste for high power package assembly. Prior to joining Heraeus, she worked in Cabot Electronic as senior scientist to develop chemical and mechanical polishing slurry. Before her Cabot assignment, she worked in Kester research and development technology as a chemist to develop SMT no clean solder paste and wave soldering flux. Dr. Zhang earned her PhD in Chemical Engineering from National University of Singapore in 2001.



Mr. Clark Dai is the Product Manager for Assembly Materials – SMT in China at Heraeus Electronics. He has a degree in Material Science and Technology from Nanjing University of Aeronautics and Astronautics, and a MBA from Keiser University in the USA. He has been with Heraeus for nearly 11 years. At Heraeus, his focus is on the electronics Assembly Materials field where he has a very strong technical and marketing experience in the area of solder pastes, adhesives, and sinter products.



Mr. Tim Lu is currently the Segment Marketing Manager for Power Electronics in APAC, focusing on Materials Solutions for customers. He studied Automation and Law at Three Gorges University. He joined Heraeus since 2014, supporting DCB business launch in China market. At Heraeus, he has held several positions, including National Sales Manager for Metal Ceramic Substrates in China and also Technical Solutions Manager for Metal Ceramic Substrates in APAC.



Mr. Song Jianbo is currently the Bonding Wire Application Lab Supervisor in China at Heraeus Electronics. He is responsible for bonding wire technical support at customer sites and in-house study. With more than 10 years of experience in semiconductor assembly industry, he is very familiar with bonding wire product features and has a very rich experience in customers application support.